WHAT IS CLAIMED IS:

1. A compression molding method for a semiconductor chip, comprising the steps of:

preparing a partition member for partitioning a cavity to form a plurality of divided cavities;

providing said partition member to be attachable to and detachable from a member forming a bottom surface of said cavity, such that a height of said partition member from the bottom surface of said cavity has a length equal to a thickness of a resin molded body to be formed, and that a resin connection path for adjusting amounts of resin in said plurality of divided cavities can function;

supplying resin into said cavity;

pressing, when pressurizing said resin in said cavity by the member forming the bottom surface of said cavity, a tip surface of said partition member onto a substrate, to adjust the amounts of resin in said plurality of divided cavities by utilizing said resin connection path; and

curing said resin to form said resin molded body having a groove having a shape corresponding to a shape of said partition member,

said resin molded body including a plurality of divided resin molded bodies partitioned by said groove, and

said plurality of divided resin molded bodies each including a semiconductor chip.

2. The compression molding method for a semiconductor chip according to claim 1, wherein

in said step of supplying resin into said cavity, said resin is supplied into all of said plurality of divided cavities at a time.

3. The compression molding method for a semiconductor chip according to claim 1, wherein

in said step of supplying resin into said cavity, said resin is individually supplied into each of said plurality of divided cavities.

4. A compression molding method for a semiconductor chip, comprising the steps of:

preparing a partition member for partitioning a cavity to form a plurality of divided cavities;

providing said partition member on a member forming a bottom surface of said cavity while elastically biasing said partition member, such that a resin connection path for adjusting amounts of resin in said plurality of divided cavities can function, and that said partition member protrudes from the bottom surface of said cavity, and setting a height of said partition member from the bottom surface of said cavity such that a tip surface of said partition member presses a substrate when pressurizing resin in said cavity by the member forming the bottom surface of said cavity;

supplying said resin into said cavity;

pressing, when pressurizing said resin in said cavity by the member forming the bottom surface of said cavity, the tip surface of said partition member onto said substrate, to adjust the amounts of resin in said divided cavities by utilizing function of said resin connection path; and

curing said resin to form a resin molded body having a groove having a shape corresponding to a shape of said partition member,

said resin molded body including a plurality of divided resin molded bodies partitioned by said groove, and

said plurality of divided resin molded bodies each including a semiconductor chip.

5. The compression molding method for a semiconductor chip according to claim 4, wherein

in said step of supplying resin into said cavity, said resin is supplied into all of said plurality of divided cavities at a time.

6. The compression molding method for a semiconductor chip according to claim 4, wherein

in said step of supplying said resin into said cavity, said resin is individually supplied into each of said plurality of divided cavities.

7. A compression mold for a semiconductor chip, comprising:

a cavity having an upward opening;

a setting portion provided above said opening, on which a substrate can be set with a semiconductor chip mounted on said substrate being directed downward;

a resin material to be supplied into said cavity;

heating means;

a mechanism for closing said substrate and said cavity to each other, to immerse the semiconductor chip mounted on said substrate in molten resin in said cavity formed by said heating means;

a cavity bottom surface member for pressurizing said molten resin in said cavity from a bottom surface side of said cavity;

a partition member provided in a predetermined position on the bottom surface of said cavity, for partitioning said cavity to form a plurality of divided cavities; and

a resin connection path for adjusting amounts of resin supplied into said plurality of divided cavities,

a height of said partition member from the bottom surface of said cavity being set to have a length equal to a predetermined thickness of a resin molded body to be formed, and said partition member corresponding to the predetermined thickness of

said resin molded body being arranged to be attachable to and detachable from said cavity bottom surface member.

8. The compression mold for a semiconductor chip according to claim 7, wherein

said resin connection path has a slit shape.

9. A compression mold for a semiconductor chip, comprising:

a cavity having an upward opening;

a setting portion provided above said opening, on which a substrate can be set with a semiconductor chip mounted on said substrate being directed downward;

a resin material to be supplied into said cavity;

heating means;

a mechanism for closing said substrate and said cavity to each other, to immerse said semiconductor chip mounted on said substrate in molten resin in said cavity formed by said heating means;

a cavity bottom surface member for pressurizing said molten resin in said cavity from a bottom surface side of said cavity;

a partition member provided in a predetermined position on the bottom surface of said cavity, for partitioning said cavity to form a plurality of divided cavities;

a resin connection path for adjusting amounts of said molten resin in said plurality of divided cavities; and

a mechanism for elastically biasing said partition member with respect to said cavity bottom surface member,

a height of said partition member from the bottom surface of said cavity being set such that a tip surface of said partition member presses a surface of said substrate when pressurizing said molten resin by said cavity bottom surface member.

10. The compression mold for a semiconductor chip according to claim 9, wherein

said resin connection path has a slit shape.

WHAT IS CLAIMED IS:

1. A compression molding method for a semiconductor chip, comprising the steps of:

preparing a compression mold for semiconductor chips;

coating a cavity provided in the compression mold with a mold release film;

providing a resin material in the cavity coated with said mold release film and heating said resin material;

immersing a semiconductor chip disposed on a substrate in said resin material in the cavity by clamping said compression mold; and

compressing said resin material in the cavity by a cavity bottom member, and molding said semiconductor chip in a resin compact having a shape corresponding to said cavity shape and a predetermined thickness;

the compression molding method further comprising the steps of:

preparing a partition member for partitioning a cavity to form a plurality of divided cavities;

providing said partition member on a member on the cavity bottom member while elastically biasing said partition member;

setting a height of said partition member from the bottom surface of said cavity such that a tip surface of said partition member presses a substrate when pressurizing resin in said cavity by the member forming the bottom surface of said cavity;

providing said cavity with a resin connection path connecting said plurality of divided cavities for adjusting the amount of the resin material in each of said divided cavities:

providing the whole area of said bottom surface of said cavity with said resin material evenly;

pressing, when pressurizing said resin in said cavity by the member forming the bottom surface of said cavity, the tip surface of said partition member onto said substrate;

adjusting, when pressing the tip surface of said partition member onto said

substrate, the amounts of resin in said divided cavities by utilizing function of said resin connection path; and

forming, when pressing the tip surface of said partition member onto said substrate, a groove having a shape corresponding to a shape of said partition member;

molding said semiconductor chip in divided resin molded bodies having a shape corresponding to said divided cavities.

2. The compression molding method for a semiconductor chip according to claim 1, wherein

in said step of supplying resin into said cavity, said resin is supplied into all of said plurality of divided cavities at a time.

3. The compression molding method for a semiconductor chip according to claim 1, wherein

in said step of supplying said resin into said cavity, said resin is individually supplied into each of said plurality of divided cavities.

4. A compression mold for a semiconductor chip, comprising:

a cavity for compression molding being provided in a compression mold for semiconductor chips and having an upward opening;

a setting portion provided above said opening, on which a substrate can be set with a semiconductor chip mounted on said substrate being directed downward;

a mold release film coating said cavity;

a resin material to be supplied into said cavity coated with said mold release film;

heating means which heats said resin material in said cavity;

a mechanism for closing said substrate and said cavity to each other, to immerse said semiconductor chip mounted on said substrate in said resin in said cavity;

a cavity bottom surface member for pressurizing said resin in said cavity from a bottom surface side of said cavity;

a partition member provided in a predetermined position on the bottom surface of said cavity, for partitioning said cavity to form a plurality of divided cavities;

a resin connection path for adjusting amounts of said resin in said plurality of divided cavities; and

a mechanism for elastically biasing said partition member with respect to said cavity bottom surface member,

a height of said partition member from the bottom surface of said cavity being set such that a tip surface of said partition member presses a surface of said substrate when pressurizing said resin by said cavity bottom surface member.

5. The compression mold for a semiconductor chip according to claim 4, wherein

said resin connection path has a slit shape.